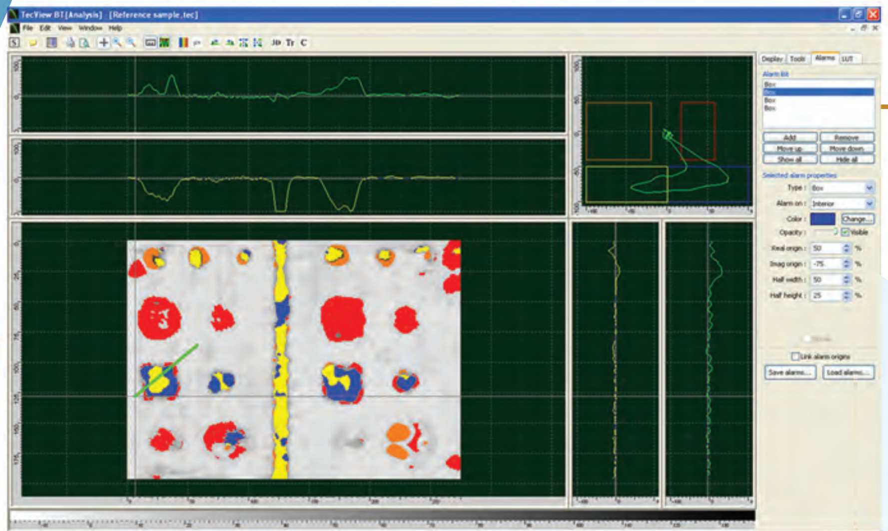
TecView™ BT

www.tecscan.ca

TecView™ BT is an advanced Bond-Testing acquisition and analysis software designed for the inspection of bond quality of aerospace composite material. With its intuitive interface, TecView™ BT automates the process of bond testing. It records the complete inspection data for reference or additional analysis and provides C-Scan imaging capabilities, which would allow more intuitive and accurate analysis possibilities in terms of defect detection, sizing and positioning.

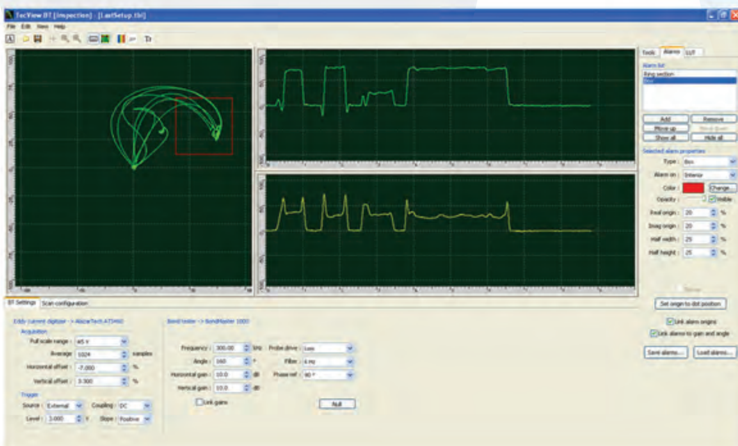


Data Acquisition

TecView™ BT is compatible with well known standard off-the-shelf Bond Testing equipment

TecView™ BT is designed to handle the whole inspection process and can perform **resonance** and **mechanical impedance** analyses.

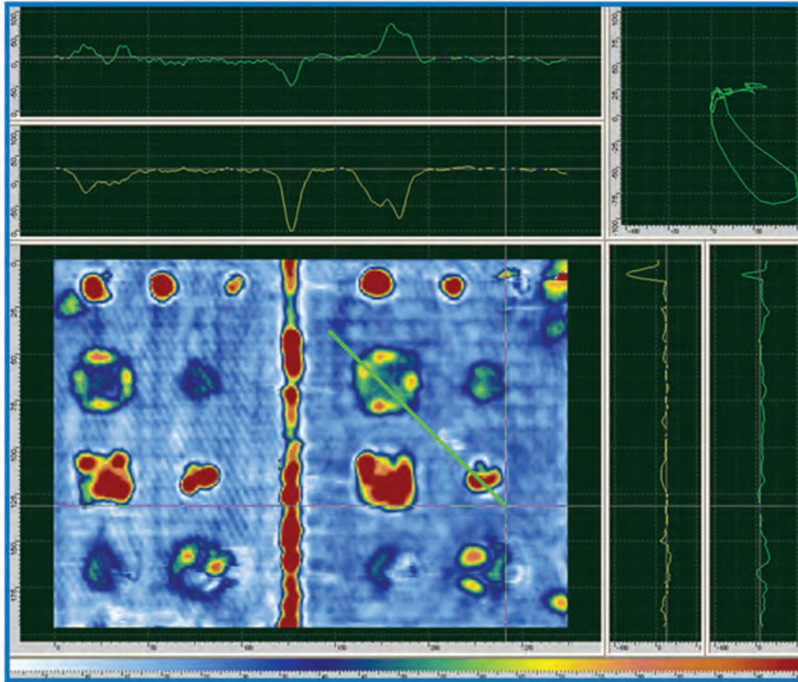
This module aids the user in the setup of all scanning parameters and includes an impedance plot section where different types of alarms can be set at once. Once all the parameters are set and the scan is started, the C-Scan, impedance plot, as well as all triggered alarms are displayed in Real-Time. A side ruler can be displayed in either Metric or Imperial systems on all data displays.



75 De Mortagne Blvd., Suite 122, Boucherville, Quebec, Canada J4B 6Y4

T•450•641•5976 | F•450•641•5873

Imaging & Data Analysis



TecView™ BT

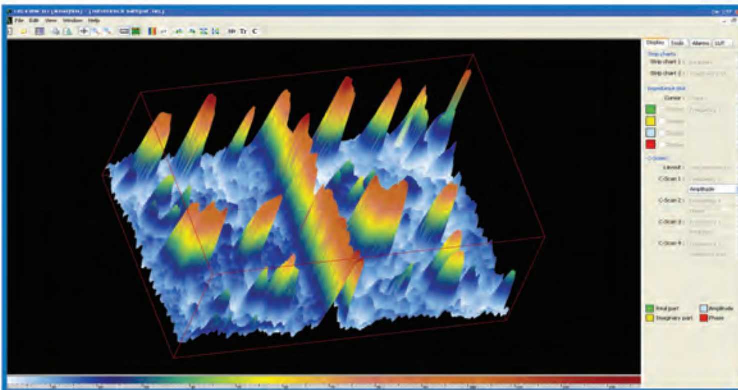
TecScan's team developed the TecView™ BT software bearing in mind versatility and efficiency. To achieve these goals, the software has a reporting utility that enables the generation and printing of custom reports that makes information sharing easy.

ARMANDA Bond Testing Solution

ARMANDA BT represents a portable Bond TestingScanner Solution. It includes TecScan's a portable automated X-Y scanner - ARMANDA, TecView™BT and a standard Bond Testing equipment, BondMaster™1000e+ from Olympus NDT, or BondaScope 3100 from NDTS Systems.

3D Analysis Module

3D projection with TecView™ BT



ARMANDA BT represents a significant addition and improvement to the bond testing market: by presenting the acquired data in a C-Scan type display and providing the ability to record and perform post-processing analysis, bond testing applications can only benefit from such an addition.

TECVIEW

- Complete multi-tasking Windows® based software
- Imaging and Analysis module
- Real-time impedance and C-Scan display
- Resonance and MIA modes
- Live Alarms utilities
- Post-processing re-nulling and rotations
- Impedance components C-Scan imaging (amplitude, phase, etc.)
- Alarm based C-Scan imaging
- 3D projection for better illustration of defects
- Reporting capabilities
- Intuitive user-interface & menu